

EAST Search History**EAST Search History (Prior Art)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S58	123943	(trench via groove hole recess opening via) with (IDL interlayer inter adj layer insulat\$4 dielectric) with (etching etch etched etch\$3 pattern patterning patter\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/24 12:13
S59	124056	(trench via groove hole recess opening via) with (IDL interlayer inter adj layer insulat\$4 interlevel intermetal dielectric) with (etching etch etched etch\$3 pattern patterning patter\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/24 12:14
S60	123943	(trench via groove hole recess opening via) with (IDL interlayer inter adj layer insulat\$4 dielectric) with (etching etch etched etch\$3 pattern patterning patter\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/25 17:15
S61	438993	(shallow near3 trench "STI" isolation near3 trench "FOX" local near oxidation field near3 oxide "LOCOS")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/05/11 08:04
S69	1	10/595384	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2012/01/13 14:29
S70	6	("20060101355" "6449749" "7024642").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2012/01/13 15:28
S71	81	("20060101355" "6449749" "7024642")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2012/01/13 15:29
S72	81	("20060101355" "6449749" "7024642")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2012/01/13 15:33
S74	68023	test near3 (chip die IC integrated near3 circuit)	US-PGPUB; USPAT;	OR	ON	2012/01/13 15:40

			USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB			
S75	2582	test near3 (chip die IC integrated near3 circuit) with test near3 structure	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2012/01/13 15:42
S76	343	test near3 (chip die IC integrated near3 circuit) with test near3 structure and array with line	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2012/01/13 15:43
S77	14141	257/48.ccls. 438/11-18.ccls. 716/51-52,56.ccls.	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2012/01/13 15:43
S78	14141	S77 and 257/48.ccls. 438/11-18.ccls. 716/51-52,56.ccls.	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2012/01/13 15:44
S79	95	S78 and test near3 (chip die IC integrated near3 circuit) with test near3 structure and array with line	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2012/01/13 15:49

1/13/2012 6:08:17 PM

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